



## TECHNOLOGY DESCRIPTION

The MID (Mechatronic Integrated Devices) technology enables the manufacturing of three-dimensional, injection-moulded circuit carriers and the integration of mechanical, electronic, thermal, fluidic, and optical functions in components of virtually any shape. The associated advantages include an increased degree of miniaturisation, the implementation of new functions and applications, and the shortening of process chains.



## INNOVATIVE ASPECTS

Spatial electronics make it possible to optimise existing systems and products with a view to the diverse requirements.

Compared to the conventional design of electronic systems on printed circuit boards, the third dimension allows more degrees of freedom in product design.

In particular, this allows savings in installation space, weight and the number of individual components required. In the case of components from the field of high-frequency technology, the third dimension makes it possible to shorten conduction paths and thus, to reduce signal losses to a minimum.



## TECHNOLOGY READINESS (in space application)

TRL 9 (2024)

## COUNTRY OF ORIGIN

Germany

## LATEST UPDATE

06/2024

**TAGS**      #miniaturisation      #weight saving      #cost saving      #injection-mould.      #3D layout      #spatial electr.

## APPLICATION AREAS

Aviation	Consumer Products	Electrical & Electronic Engineering	Food & Agriculture	Health	Maritime & Aquatic	Safety & Security
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SPACE  
FOR BUSINESS  
BUSINESS  
FOR SPACE

# TECH CARD

